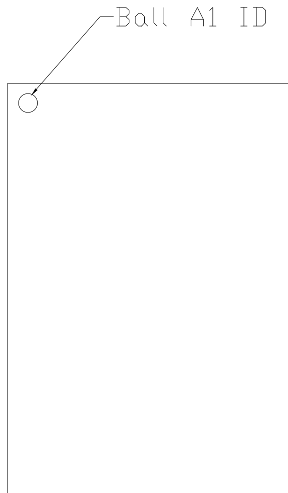
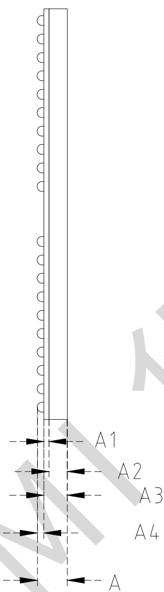
RoHS

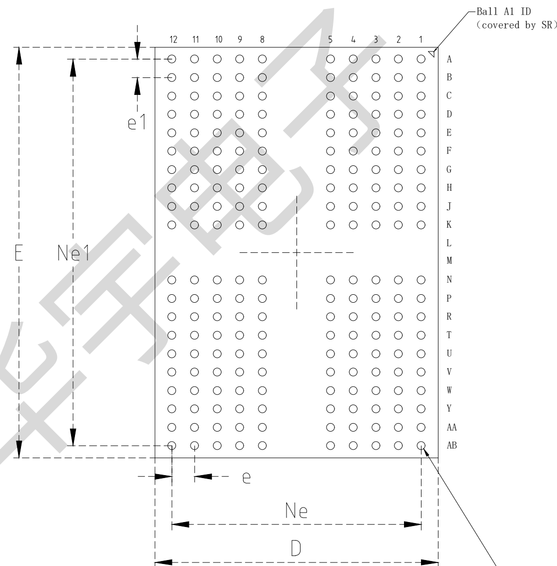
TOP VIEW
正视图



SIDE VIEW
侧视图



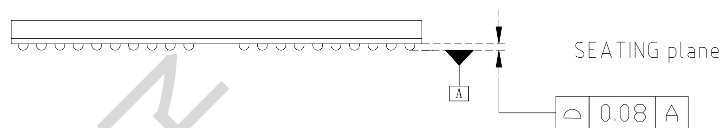
BOTTOM VIEW
背视图



机械尺寸/mm			
字符 SYMBOL	最小值 MIN	典型值 NOMINAL	最大值 MAX
A	1.00	1.100	1.200
A1	0.150	0.180	0.210
A2	0.060	0.650	0.700
A3	0.078	0.830	0.880
A4	0.175	0.225	0.275
b	0.350 REF		
D	9.900	10.000	10.100
E	14.400	14.500	14.600
e	0.650 BSC		
e1	0.800 BSC		
Ne	8.800 REF		
Ne1	13.650 REF		

200Xφ0.35(b)±0.05
dimensions apply
to solder balls
postreflow on
φ0.28 SMD BALL
pads

SIDE VIEW
侧视图



池州华宇电子科技股份有限公司 CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD				制图: Draw	NINGLIN 2025.11.25
HY-POD-BGA0114				制图核查: Drawing review	
PACKAGE OUTLINE DIMENSIONS FBGA200B(14.5X10x1.1-P0.65)				审核: Checker	
页数 page	单位 unit	比例 scale	视图 view	核准: Approved	
1	mm	1:1			

HISEMI 华宇电子